

### **FEATURES**

- ◆ Fast switching for high efficiency
- ♦ Low noise
- ♦ Trr ~ 20ns
- Ultra low reverse leakage current
- High voltage ultra faster diode PFC application
- ♦ High inrush current

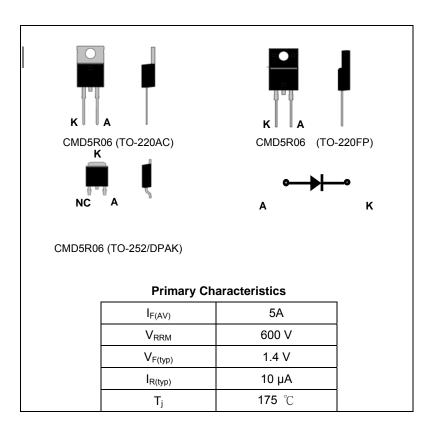
### **MECHANICAL DATA**

 Case : Molded plastic TO-220AC / TO-220FP

Epoxy: UL94V-0 rate flame retardant
Terminals: Solder able per MIL-STD-202 method 208

♦ 265°C Max. for 10 Seconds

◆ Maximum Mounting Torque 6 ( 5 ) Kg-cm( lbf-in )



### ORDERING INFORMATION

Part Number	Temperature Range	Package
CMD5R06XN220*	-55°C to 175°C	TO-220AC
CMD5R06XN220FP*	-55°℃ to 175°℃	TO-220FP
CMD5R06XN252*	-55°C to 175°C	TO-252

<sup>\*</sup>Note : X : Suffix for Halogen Free



### **MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

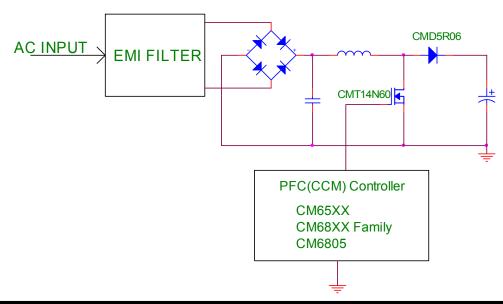
Ratings at  $25^{\circ}$ C ambient temperature unless otherwise specified. Single phase, half wave , 60Hz , resistive or inductive load. For capacitive load , derate current by 20%

Cumbal	Characteristics		CMD5R06	Unit	
Symbol	Characte	eristics	Rating	Unit	
$V_{RRM}$	Recurrent Peak Reverse Voltage	e	600	V	
$V_{DC}$	DC Blocking Voltage	C Blocking Voltage 600		V	
IF <sub>(AV)</sub>	Average Forward Rectified Current @Tc=140°C 5.0		А		
I <sub>FSM</sub>	Peak Forward Surge Current 8.3ms single half sine-wave Super imposed on rated load (J	EDEC Method)	70	А	
I <sub>FSM</sub>	Peak Forward Surge Current 1. Square-wave superimposed on	· ·	100	А	
I <sup>2</sup> t	I <sup>2</sup> t Value For Fusing	Tp=10ms	91	A <sup>2</sup> s	
V <sub>F</sub>	Instantaneous Forward Voltage (Typical) @5A		1.4	V	
	DC Reverse Current @T <sub>J</sub> =25°C		10		
I <sub>R</sub>	At Rated DC Blocking Voltage	@T <sub>J</sub> =150℃	45	uA	
Trr	Maximum Reverse Recovery Ti	me (note1)	25	nS	
$C_{J}$	Typical Junction Capacitance (note2)		36	pF	
$R_{ heta JC}$	Typical Thermal Resistance (note3)		2.2	°C/W	
TJ	Operating Temperature Range		-55~+175	$^{\circ}$	
T <sub>STG</sub>	Storage Temperature Range		-55~+175	$^{\circ}$	
$R_{ heta JA}$	Typical Thermal Resistance	TO-220AC TO-220FP	60 50	$^{\circ}$	
		TO-252	80		

Notes : 1. Reverse recovery test conditions  $I_F$ =0.5A ,  $I_F$ =1.0A ,  $I_F$ =0.25A

- 2. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts DC.
- 3. Thermal Resistance junction to case.

# **Application Circuit**





### TYPICAL CHARACTERISTICS

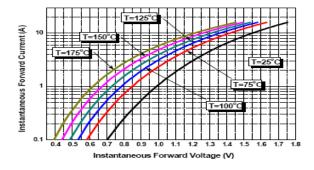


Figure 1. Typical Forward voltage V.S current

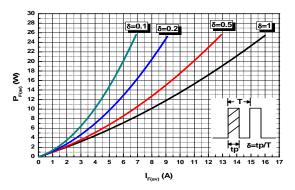


Figure 3. Average Forward Power Dissipation per Diode

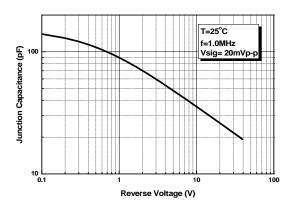


Figure 5. Typical Junction Capacitance

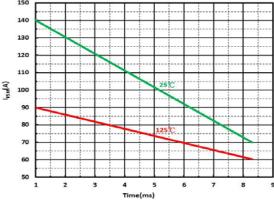


Figure 7. Peak forward surge current (single half sine wave)

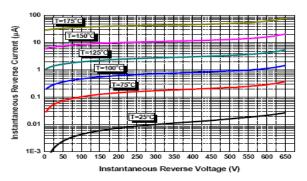


Figure 2. Typical Reverse Characteristics per Diode

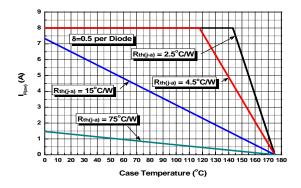


Figure 4. Current derating Curves

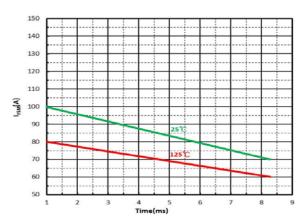
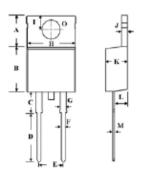


Figure 6. Peak forward surge current (square-wave)



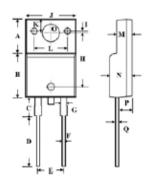
## **PACKAGE DIMENSION**

TO-220AC



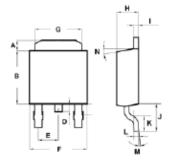
Dimension	Millimeters		Dimension	Millimeters	
	Min.	Max.	Dilliension	Min.	Max.
Α	6.173	6.515	Н	10.01	10.31
В	8.763	9.017	I	2.642	2.946
С	3.98	4.423	J	1.168	1.37
D	9.72	9.87	K	4.47	4.67
E	4.98	5.18	L	2.52	2.82
F	0.711	0.91	М	0.279	0.483
G	1.17	1.37	0	3.77	3.89

TO-220FP



Dimension	Millimeters		Dimension	Millimeters	
	Min.	Max.	Dimension	Min.	Max.
Α	6.40	6.80	J	9.90	10.10
В	8.40	8.60	K	2.55	2.85
С	3.45	3.75	L	6.50	6.70
D	9.55	10.05	М	2.90	3.30
E	4.98	5.18	N	4.20	4.80
F	0.50	0.75	0	2.90	3.50
G	1.15	1.35	Р	2.50	2.90
Н	10.25	10.55	Q	0.58	0.62
I	0.30	0.40			

# TO-252(DPAK)



Dimension	Millimeters		Dimension	Millimeters	
	Min.	Max.	Dilliension	Min.	Мах.
Α	0.89	1.27	Н	2.19	2.38
В	5.97	6.22	I	0.46	0.58
С	1.15	1.52	J	2.43	2.83
D	0.64	1.02	K	1.39	1.65
E	2.19	2.39	L	0.44	0.60
F	6.35	6.73	М	0°	10°
G	5.21	5.46	N	0°	15 <sup>0</sup>



### **IMPORTANT NOTICE**

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